

STARPOWER

SEMICONDUCTOR

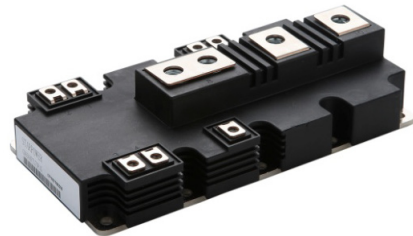
IGBT

GD900HFT120P1S

1200V/900A 2 in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as electric vehicle and solar power.



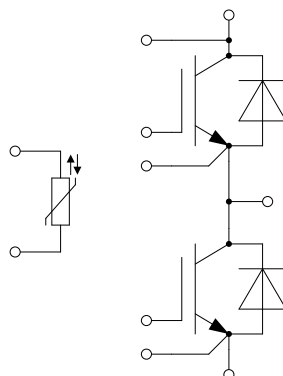
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- 10 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Isolated copper baseplate using DBC technology
- High power and thermal cycling capability

Typical Applications

- High Power Converter
- Solar Power
- Hybrid and Electric Vehicle

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**IGBT**

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=100^{\circ}\text{C}$	1300 900	A
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	1800	A
P_D	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	4.97	kW

Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	900	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	1800	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	$^{\circ}\text{C}$
T_{jop}	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	4000	V

IGBT Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=900\text{A}, V_{GE}=15\text{V}, T_j=25^{\circ}\text{C}$		1.70	2.05	V
		$I_C=900\text{A}, V_{GE}=15\text{V}, T_j=125^{\circ}\text{C}$		2.00		
		$I_C=900\text{A}, V_{GE}=15\text{V}, T_j=150^{\circ}\text{C}$		2.10		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=34.2\text{mA}, V_{CE}=V_{GE}, T_j=25^{\circ}\text{C}$	5.0	5.8	6.5	V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$			5.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^{\circ}\text{C}$			400	nA
R_{Gint}	Internal Gate Resistance			1.5		Ω
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=1\text{MHz}, V_{GE}=0\text{V}$		55.4		nF
C_{res}	Reverse Transfer Capacitance			3.11		nF
Q_G	Gate Charge	$V_{GE}=-15\dots+15\text{V}$		6.40		μC
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=900\text{A}, R_G=1.3\Omega, V_{GE}=\pm 15\text{V}, T_j=25^{\circ}\text{C}$		198		ns
t_r	Rise Time			142		ns
$t_{d(off)}$	Turn-Off Delay Time			705		ns
t_f	Fall Time			198		ns
E_{on}	Turn-On Switching Loss			70.6		mJ
E_{off}	Turn-Off Switching Loss			125		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=900\text{A}, R_G=1.3\Omega, V_{GE}=\pm 15\text{V}, T_j=125^{\circ}\text{C}$		220		ns
t_r	Rise Time			152		ns
$t_{d(off)}$	Turn-Off Delay Time			798		ns
t_f	Fall Time			410		ns
E_{on}	Turn-On Switching Loss			101		mJ
E_{off}	Turn-Off Switching Loss			160		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=900\text{A}, R_G=1.3\Omega, V_{GE}=\pm 15\text{V}, T_j=150^{\circ}\text{C}$		222		ns
t_r	Rise Time			153		ns
$t_{d(off)}$	Turn-Off Delay Time			845		ns
t_f	Fall Time			446		ns
E_{on}	Turn-On Switching Loss			104		mJ
E_{off}	Turn-Off Switching Loss			176		mJ
I_{SC}	SC Data	$t_p \leq 10\mu\text{s}, V_{GE}=15\text{V}, T_j=150^{\circ}\text{C}, V_{CC}=800\text{V}, V_{CEM} \leq 1200\text{V}$		3600		A

Diode Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=900\text{A}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$		1.65	2.00	V
		$I_F=900\text{A}, V_{GE}=0\text{V}, T_j=125^{\circ}\text{C}$		1.75		
		$I_F=900\text{A}, V_{GE}=0\text{V}, T_j=150^{\circ}\text{C}$		1.70		
Q_r	Recovered Charge	$V_R=600\text{V}, I_F=900\text{A},$ $-di/dt=4500\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=25^{\circ}\text{C}$		150		μC
I_{RM}	Peak Reverse Recovery Current			525		A
E_{rec}	Reverse Recovery Energy			45.0		mJ
Q_r	Recovered Charge	$V_R=600\text{V}, I_F=900\text{A},$ $-di/dt=4500\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=125^{\circ}\text{C}$		255		μC
I_{RM}	Peak Reverse Recovery Current			690		A
E_{rec}	Reverse Recovery Energy			80.0		mJ
Q_r	Recovered Charge	$V_R=600\text{V}, I_F=900\text{A},$ $-di/dt=4500\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=150^{\circ}\text{C}$		315		μC
I_{RM}	Peak Reverse Recovery Current			750		A
E_{rec}	Reverse Recovery Energy			100		mJ

NTC Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			5.0		k Ω
$\Delta R/R$	Deviation of R_{100}	$T_C=100^{\circ}\text{C}, R_{100}=493\Omega$	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K

Module Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
L_{CE}	Stray Inductance		18		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal to Chip		0.30		m Ω
$R_{\theta JC}$	Junction-to-Case (per IGBT) Junction-to-Case (per Diode)			30.2 52.2	K/kW
$R_{\theta CS}$	Case-to-Sink (per IGBT) Case-to-Sink (per Diode)		14.2 24.6		K/kW
$R_{\theta CS}$	Case-to-Sink		4.5		K/kW
M	Terminal Connection Torque, Screw M4	1.8		2.1	N.m
	Terminal Connection Torque, Screw M8	8.0		10	
	Mounting Torque, Screw M5	3.0		6.0	
G	Weight of Module		825		g

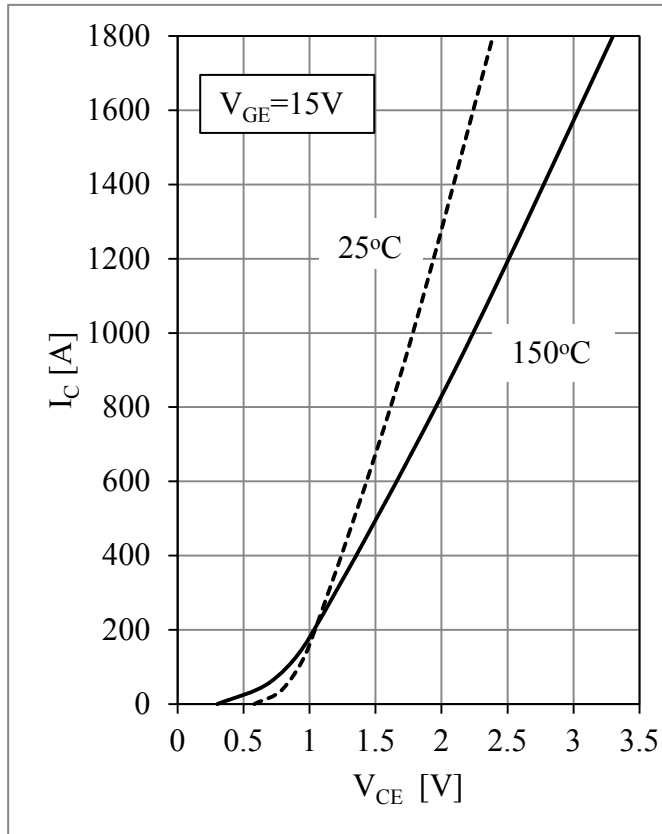


Fig 1. IGBT Output Characteristics

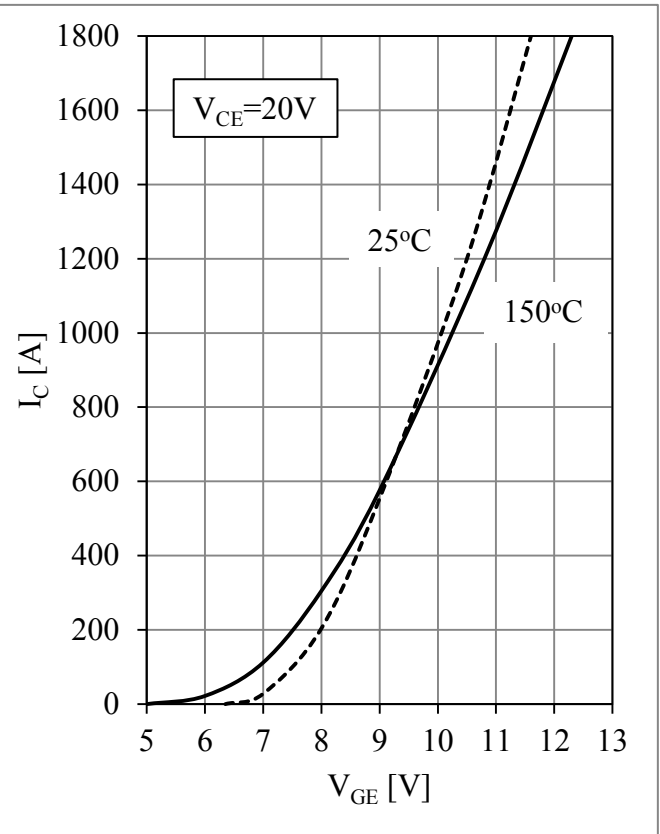
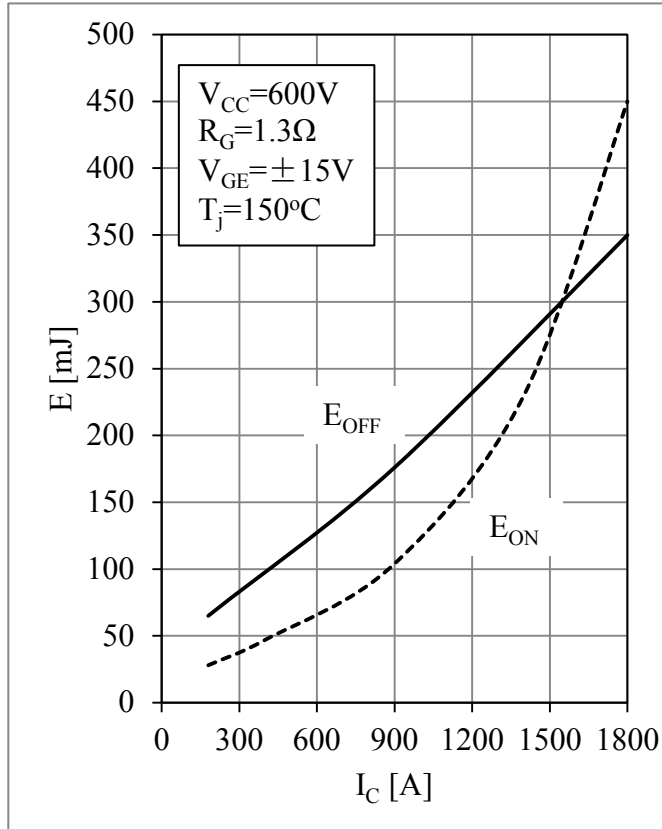
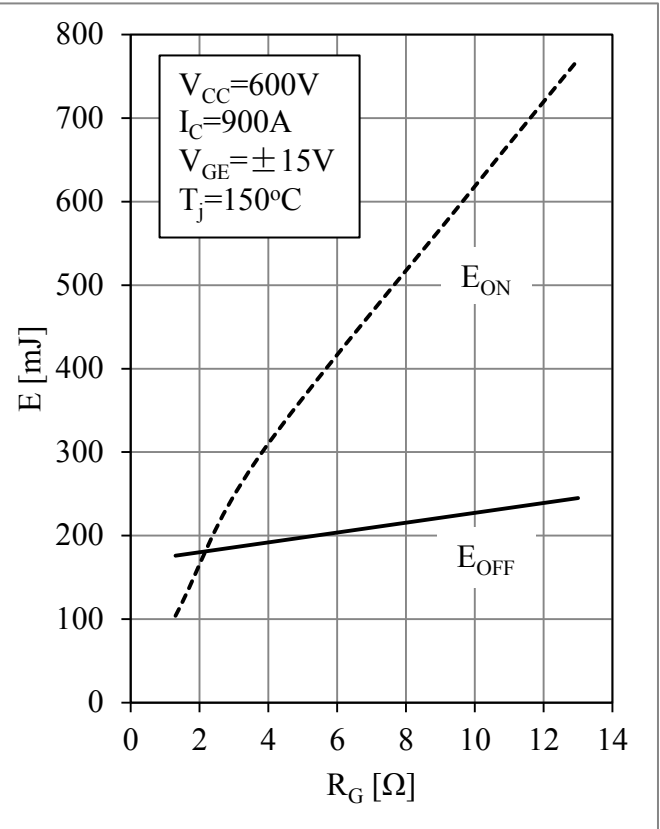


Fig 2. IGBT Transfer Characteristics

Fig 3. IGBT Switching Loss vs. I_C Fig 4. IGBT Switching Loss vs. R_G

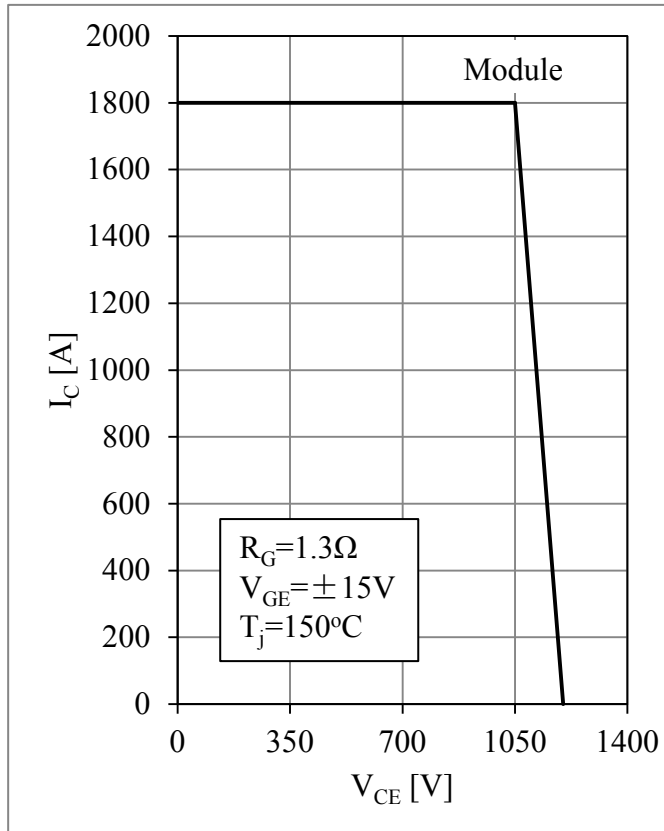


Fig 5. RBSOA

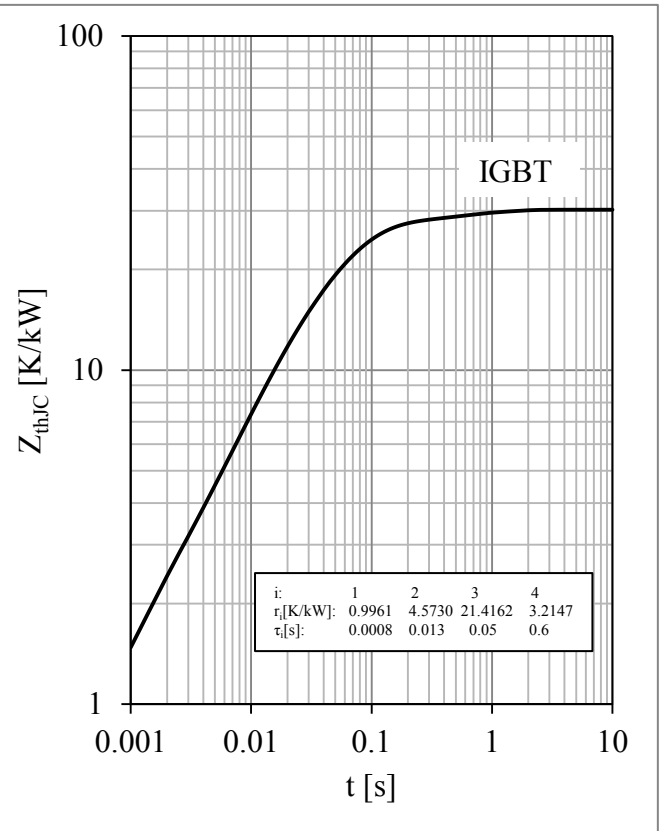


Fig 6. IGBT Transient Thermal Impedance

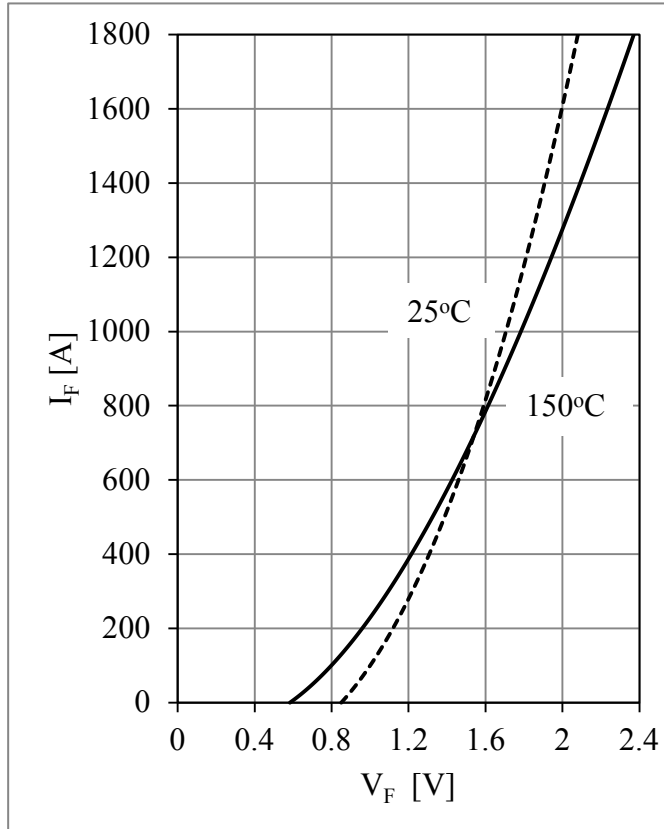
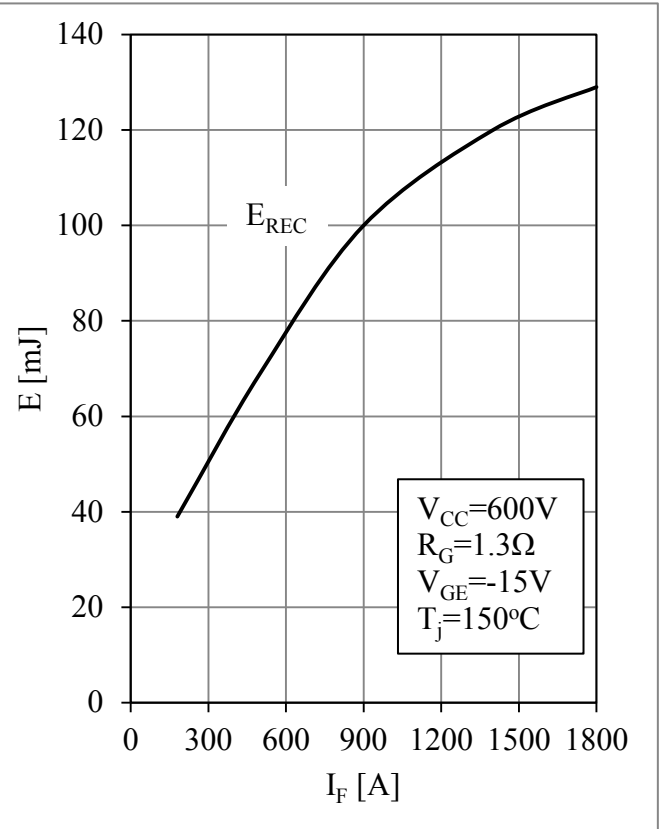
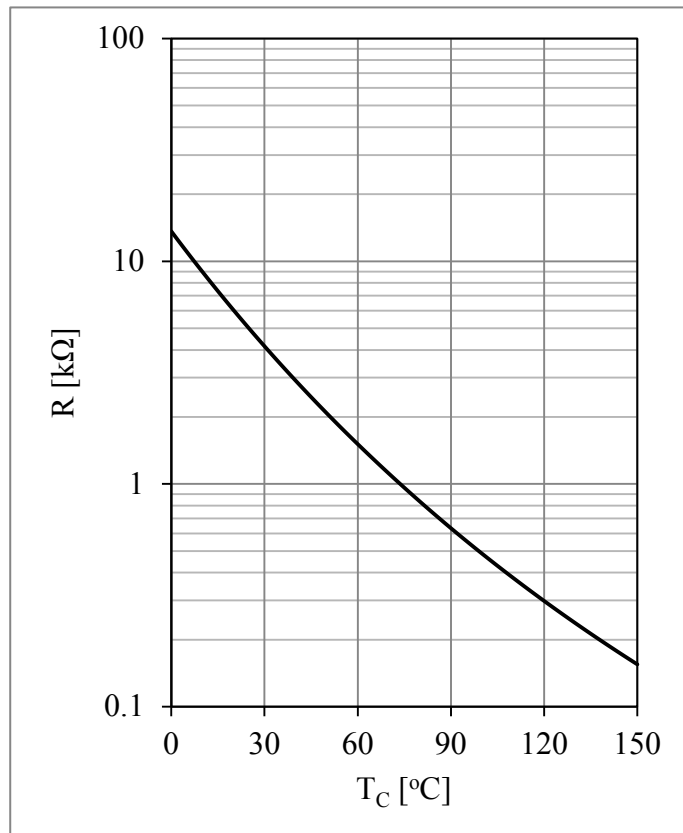
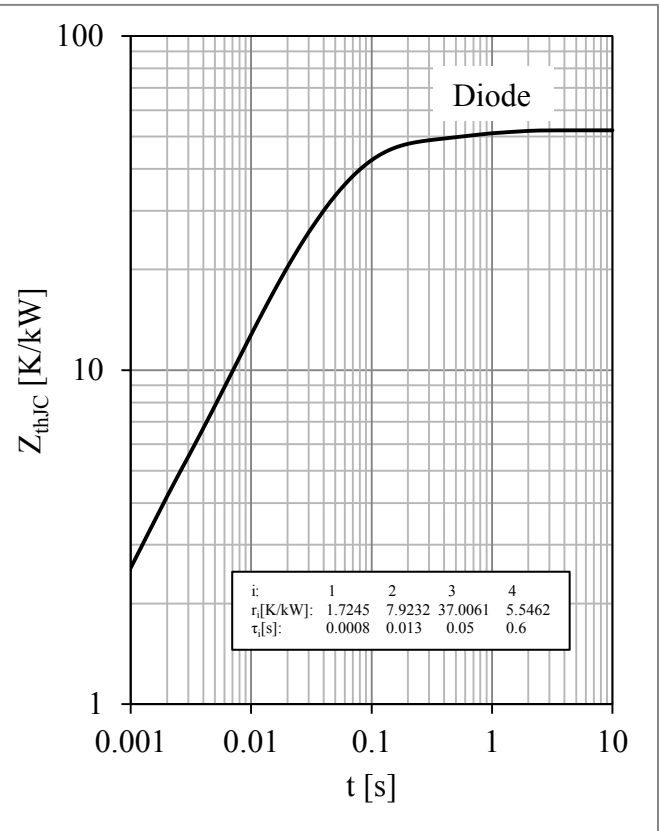
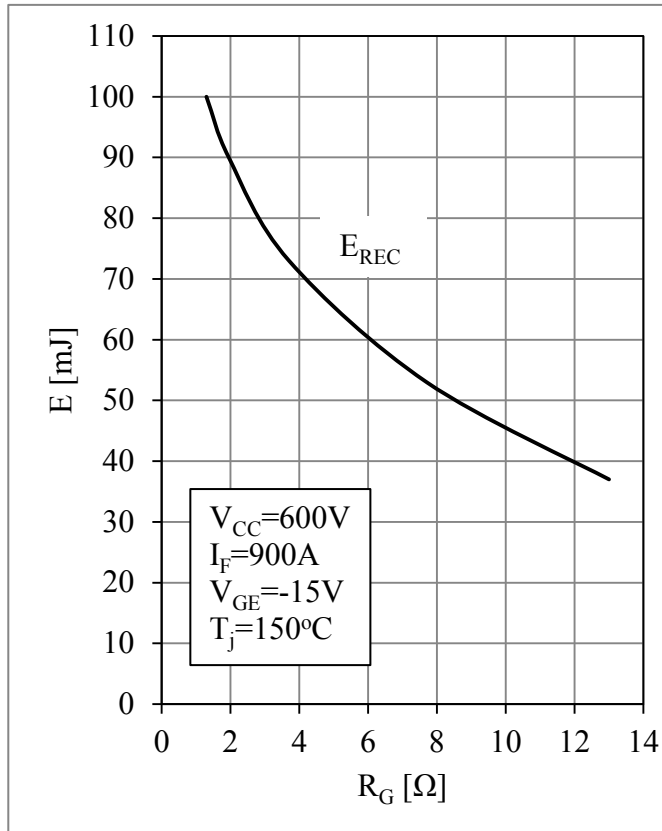


Fig 7. Diode Forward Characteristics

Fig 8. Diode Switching Loss vs. I_F



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